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■ Power Inductor — EBP1265A-TWA Series

AEC-Q200 Qualified



Application

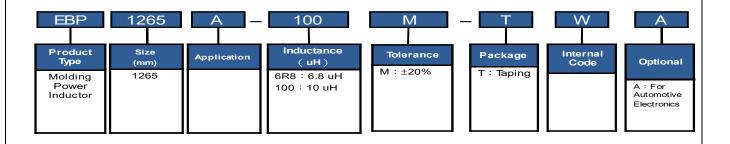
- Laptops and PCs
- Switch and servers
- Base stations
- DC/DC converters
- Battery powered devices
- SSD modules

Features

- ROHS , Halogen Free and REACH compliance.
- High rated current.
- Operating temperature -55°C∼+155°C(Including self temperature rise) .
- Low core loss.
- Ultra low buzz noise due to molding construction.
- High reliability -Reliability test complied to AEC-Q200

Parts Number Explanation

Example:





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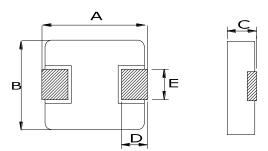
Standard Electrical Specifications

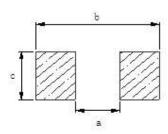
Dord No.	Inductance	DC Resistance	Saturation Current	Heating Rating Current
Part No.	L0 (µH)	DCR (mΩ)	Isat (A)	Irms (A)
	±20 %, 100 kHz, 1V	MAX.	TYP.	TYP.
EBP1265A-6R8M-TWA	6.8	12	19	13
EBP1265A-100M-TWA	10	16.5	13.5	12

Notes:

- 1. All test data is referenced to 25 °C ambient
- 2. Operating temperature range 55 °C to + 155 °C
- 3. Irms (A):DC current (A) that will cause an approximate ΔT of 40 °C(reference ambient temperature is 25 °C)
- 4. Isat(A):DC current (A) that will cause L0 to drop approximately 30 %
- 5. The part temperature (ambient + temp rise) should not exceed 155 °C under worst case operating conditions. Circuit design, component placement, PWB trace size and thickness, airflow and other cooling provisions all affect the part temperature. Part temperature should be verified in the end application.

Dimensions





Recommend Land Pattern

Unit: mm

Туре	Α	В	С	D	Е	a typ	b typ	c typ
EBP1265A	13.45 ±0.35	12.6 ±0.3	6.5 ±0.2	2.0 ±0.5	5.0 ±0.3	8.0	14.5	5.5



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■ Marking

• The inductor is marked with a 3-digit code

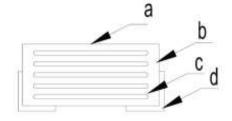
Nominal Inductance	
Example	Nominal Value
1R0	1.0 µH
100	10 µH
101	100 µH



Note: Using Ink for marking

■ Structure and Components

Symbol	Components	Material
а	MARKING	Ink (black)
b	CORE	Alloy Sponge Powder
С	WIRE	Polyurethane copper wire
d	TERMINAL	Copper plated with Sn





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Reliability test and requirement

Mechanical Reliability			
Item	Specification and Requirement	Test Method	
Solderability	No case deformation or change in appearance New solder coverage More than 95%	1.Preheat: $155\%\pm5\%$, $608\pm2\$$ 2.Tin: lead-free. 3.Temperature:240 $\%\pm5\%$, flux 3.0 $\$\pm0.5\$$.	
Mechanical shock	No case deformation or change in appearance ∴L/Lo≦±10%	1. Acceleration: 100G 2. Pulse time: 6ms 3. 3 times in each positive and negative direction of 3 mutual perpendicular directions	
Mechanical vibration	No case deformation or change in appearance △L/Lo≦±10%	1. Reflow: 2times 2. Frequency: 10HZ~55HZ~10HZ, 20 Min/Cycles 3. Amplitude: 1.52 mm 4. Directions: X,Y,Z 5. Time: 12 cycle / direction	

Endurance Reliability

Item	Specification and Requirement	Test Method
Thermal Shock	Inductance change: Within ± 10% Without distinct damage in appearance	 First -55℃ for 30 minutes, last 155℃ for 30 minutes as 1 cycle. Go through 1000 cycles. Max transfer time is 3 minutes. Measured at room temperature after placing for 24±2 hours
Humidity Resistance	Inductance change: Within ± 10% Without distinct damage in appearance	1.Reflow 2 times, 2.85 °C,85%RH,1000 hours 3.Measured at room temperature after placing for 24 ± 2 hours
Low temperature storage	Inductance change: Within ± 10% Without distinct damage in appearance	1. Temperature: -55 \pm 2°C 2. Time: 1000 hours 3. Measured at room temperature after placing for 24 \pm 2 hours
High temperature storage	Inductance change: Within ± 10% Without distinct damage in appearance	1. Temperature: +155 \pm 2°C 2. Time: 1000 hours 3. Measured at room temperature after placing for 24 \pm 2 hours



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Recommended Soldering Technologies:

(1) Re-flowing Profile

Preheat condition: 150 ~200°C/60~120sec.

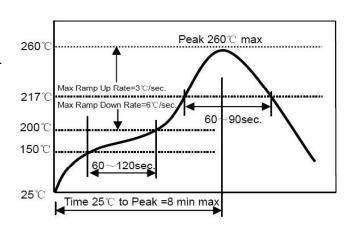
Allowed time above 217°C: 60~90sec.

Max temp: 260°C

Max time at max temp: 10 sec.

Solder paste: Sn/3.0Ag/0.5Cu

Allowed Reflow time: 2x max



(2) Iron Soldering Profile

Iron soldering power: Max. 30W

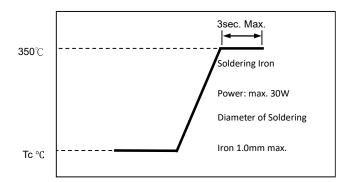
Pre-heating: 150°C/60sec.

Soldering Tip temperature: 350°C Max.

Soldering time: 3sec. Max.

Solder paste: Sn/3.0Ag/0.5Cu

Max.1 times for iron soldering

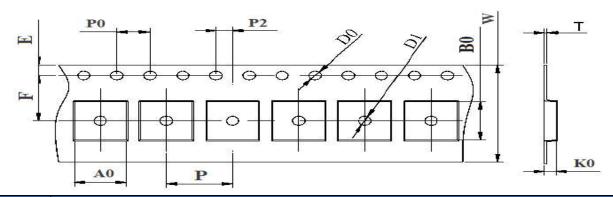




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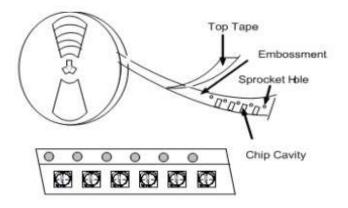
■ Packaging Information

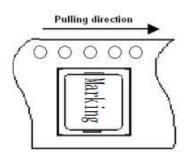
(1) Tape Packaging Dimensions (Unit: mm)



Туре		Tape dimensions (mm)										
71.	W	Р	P0	P2	D0	D1	T	A0	В0	K0	Е	F
EBP1265A	24±0.3	16±0.1	4.0±0.1	2.0±0.05	1.5±0.1	1.5±0.1	0.5±0.05	13.1±0.1	14.0±0.1	6.8±0.1	1.75±0.1	11.5±0.1

(2) Taping Drawings (Unit: mm)

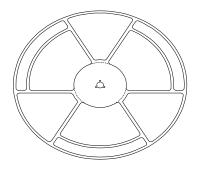


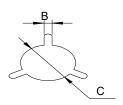


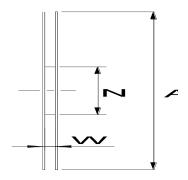


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(3) Reel Dimensions (Unit: mm)







Type	Reel dimensions (mm)						
-716-3	Α	W	N	В	С		
EBP1265A	330 +2.0	24.0 ±0.5	97.0 ±0.5	2.2 +0.5	13.0 ±0.2		

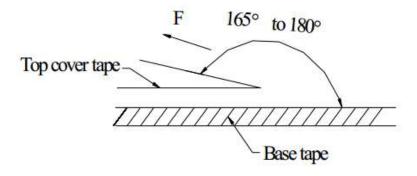
(4) Packaging Quantity(PCS)

Type	Standard Quantity				
туре	Reel	Inner box	Carton box		
EBP1265A	500 pcs / reel	2Reel / box (1,000 pcs)	4 Middle boxes, (4,000 pcs)		

(5) Peel force of top cover tape

The peel speed shall be about 300mm/minute

The peel force of top cover tape shall be between 0.1 to 1.3 N

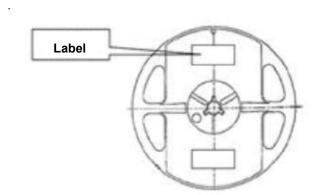




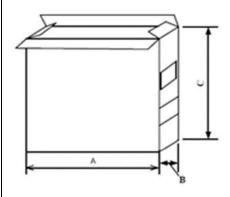
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(6) Reel Label

- ●Label on the reel
- Everohms part Number.
- Lot Number
- Quantity
- Description
- ●Shipping Label
- Customer's part Number
- Manufacturer's part Number
- Quantity
- date code

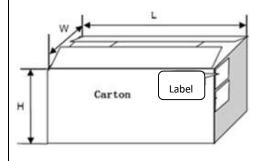


(7) Inner Box



Packaging Type	A (mm)	B (mm)	C (mm)
Inner box	335	70	340

(8) Carton



Packaging Type	L (mm)	W (mm)	H (mm)
Carton	360	360	360